



M.E DEGREE EXAMINATIONS: JUNE 2017

(Regulation 2015)

Second Semester

APPLIED ELECTRONICS

P15AET203 : ASIC Design

COURSE OUTCOMES

- CO1:** Describe different types of ASICs
- CO2:** Illustrate internal architecture of commercially available FPGAs.
- CO3:** Develop algorithms to implement digital design on FPGAs
- CO4:** Distinguish various steps in FPGA design implementation
- CO5:** Evaluate case studies of FPGA architectures and logic synthesis

Time: Three Hours

Maximum Marks: 100

Answer all the Questions:-

PART A (10 x 1 = 10 Marks)

1. Assertion (A): In profit model, total sales is increased if product is introduced in time. CO1 [K2]
Reason (R): In profit model, total sales is declined if product is introduced in delayed time.
 - a) both A and R are individually true and R is the correct explanation of A
 - b) both A and R are individually true but R is not the correct explanation of A
 - c) A is true but R is false
 - d) A is false but R is true.
2. CBIC contains CO1 [K2]
 - a) Standard AND gates
 - b) Standard AND, OR gates MUX, Flip Flops
 - c) Standard OR gates
 - d) Standard XOR gates
3. ONO stands for CO2 [K1]
 - a) Oxide-Nitride-Oxide
 - b) Oxide-Nitrogen=Oxygen
 - c) Oxygen-Nitrogen=Oxygen
 - d) Oxide-Nitride-Oxygen
4. Matching type item with multiple choice code CO2 [K3]

| List I | List II |
|------------------|-------------------------|
| A. Antifuse | i. Metal-Metal Antifuse |
| B. Amorphous Si | ii. EPROM Erase |
| C. Floating gate | iii. FPGA |
| D. UV ray | iv. EEPROM technology |

| | A | B | C | D |
|----|-----|----|-----|----|
| a) | ii | i | iii | iv |
| b) | iii | iv | ii | i |
| c) | ii | iv | iii | i |
| d) | iii | i | iv | ii |

5. Assertion (A): AC output IO cell can drive very high speed devices. CO3 [K4]

Reason (R): AC output IO cell works on frequency less than 1Mhz.

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|---|---|
| a) Both A and R are Individually true and R is the correct explanation of A | b) Both A and R are Individually true but R is not the correct explanation of A |
| c) A is true but R is false | d) A is false but R is true |

6. $V_{IH(min)}$ and $V_{IL(max)}$ for TTL logic are CO3 [K1]

- | | |
|--------------------|------------------|
| a) 2.0 V and 0.8 V | b) 2.2V and 0.8V |
| c) 0.8V and 2.0V | d) 0.8V and 2.2V |

7. Multiple selection item with multiple choice code CO4 [K2]

In Xilinx LCA:

1. Vertical and horizontal lines run only above CLBs.
2. Genera-purpose interconnect joins switch boxes.
3. Long lines run across entire chip.
4. Direct connections pass through the switch matrices.

Identify the correct statements.

- | | |
|----------|----------|
| a) 1 & 3 | b) 1 & 4 |
| c) 1& 2 | d) 2 & 3 |

8. Sheet resistance and line capacitance of aluminium metallization used in programmable interconnect are: CO4 [K2]

- | | |
|-----------------------------------|------------------------------------|
| a) 500 milliohm/square and 2pF/cm | b) 50milliohm/square and 0.2pF/cm |
| c) 5milliohm/square and 0.2pF/cm | d) 500milliohm/square and 0.2pF/cm |

9. Four value logic system are CO5 [K2]

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|--------------------------|---------------------|
| a) 0, 1, X & Z | b) 0, 1, weak-0 & Z |
| c) 0, 1, weak-0 & weak-1 | d) 0, 1, X & weak-1 |

10. Sequence the following EDA process correctly CO5 [K4]

1. Synthesize
2. Simulation
3. Schematic /coding entry
4. compilation

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|------------|------------|
| a) 2-3-4-1 | b) 1-3-2-4 |
| c) 3-4-2-1 | d) 4-1-3-2 |

PART B (10 x 2 = 20 Marks)

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|--|-----|-------------------|
| 11. Differentiate full custom and semi custom design. | CO1 | [K ₄] |
| 12. List out the various types of parasitic capacitances in MOS transistor. | CO1 | [K ₂] |
| 13. Write the part naming convention of Xilinx FPGA XC4010-10 PG156C, | CO2 | [K ₃] |
| 14. Draw the architecture view of Logic Array Block used in Altera Max device. | CO2 | [K ₃] |
| 15. Justify the need for CLOCK and POWER IO cell in FPGA. | CO3 | [K ₃] |
| 16. Why clamp diodes are required in DC output IO cell of FPGA? | CO3 | [K ₃] |
| 17. Tell the applications of programmable interconnect. | CO4 | [K ₁] |
| 18. Illustrate simple RC delay model of antifuse connections. | CO4 | [K ₃] |
| 19. What are the types of simulations? | CO5 | [K ₁] |
| 20. What is logic synthesis? | CO5 | [K ₂] |

PART C (6 x 5 = 30 Marks)

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|---|-----|-------------------|
| 21. Describe the working of Flip Flop in sequential logic cell with circuit diagram and waveform. | CO1 | [K ₂] |
| 22. Illustrate Shannon's expansion theorem with suitable example. | CO2 | [K ₃] |
| 23. Illustrate the supply bounce issue in AC output IO cell with necessary circuit and waveform. | CO3 | [K ₄] |
| 24. Analyse the performance of AC output IO cell for parasitic capacitance when system is with few chips that are connected by tri-state bus. | CO3 | [K ₄] |
| 25. Describe the interconnect architecture of Altera Max 9000 with required diagram. | CO4 | [K ₂] |
| 26. Describe with simulation cycle steps how logic simulation works? | CO5 | [K ₂] |

Answer any FOUR Questions

PART D (4 x 10 = 40 Marks)

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|--|-----|-------------------|
| 27. Design 6-bit array multiplier using appropriate adder circuit and explain the working with block diagram. | CO1 | [K ₃] |
| 28. Explain the internal architecture of CLB used in XC4000 FPGA with necessary diagram. | CO2 | [K ₂] |
| 29. Elaborate on timing model of CLOCK signal with necessary diagram for registered input and output configuration. | CO3 | [K ₂] |
| 30. Draw and explain the interconnect architecture and components of interconnect delay in Xilinx LCA array. | CO4 | [K ₂] |
| 31. Illustrate with suitable example for synthesis of any one combinational and sequential logic using VHDL. Use any type of modeling. | CO5 | [K ₄] |
